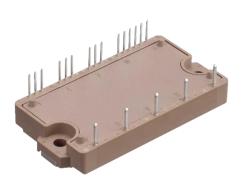


**IGBT Modules** 

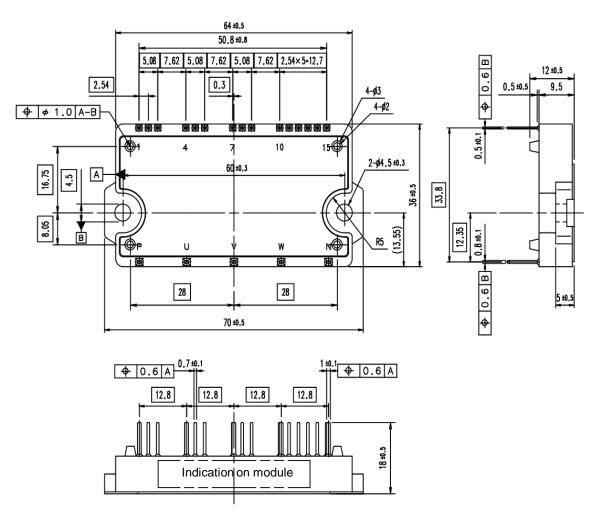
### IGBT Module (X series) 650V / 30A / IPM

#### ■ Features

- Temperature protection provided by directly detecting the junction temperature of the IGBTs
- ·Low power loss and soft switching
- ·High performance and high reliability IGBT with overheating protection
- Higher reliability because of a big decrease in number of parts in built-in control circuit



#### ■ Outline drawing (Unit:mm)



Weight:55g(typ.)



**IGBT Modules** 

#### ■ Absolute maximum ratings

 $T_{\rm C}$ =25°C,  $T_{\rm vi}$ =25°C,  $V_{\rm CC}$ =15V unless otherwise specified

	İtems	Symbol	Conditions	Min.	Max.	Units
Co	ollector-emitter voltage	$V_{CES}$	*1	-	650	V
Sh	ort circuit voltage	$V_{ m SC}$	*2	200	400	V
Ŀ		$I_{C}$	DC	-	30	Α
)rte	Collector current	I <sub>CP</sub>	1ms	-	60	Α
Inverter		-/ <sub>C</sub>	Duty=100% *3	-	30	Α
三	Total power dissipation	$P_{\text{tot}}$	IGBT 1 device *4	-	133	W
	Collector current	$I_{C}$	DC	-	-	Α
Brake		I <sub>CP</sub>	1ms	-	-	Α
Bra	Forward current of diode	I <sub>F</sub>		-	-	Α
	Total power dissipation	$P_{\text{tot}}$	IGBT 1 device *4	-	-	W
Sι	ipply voltage of pre-driver	V <sub>cc</sub>	*5	-0.5	20	V
Inp	out signal voltage	$V_{in}$	*6	-0.5	$V_{\rm CC} + 0.5$	V
Ala	arm signal voltage	$V_{ALM}$	*7	-0.5	$V_{CC}$	٧
Ala	arm signal current	I <sub>ALM</sub>	*8	-	20	mΑ
Vir	tual junction temperature	$T_{vj}$		-	175	°C
Op	perating virtual junction temperature	$T_{\text{vjop}}$		-	150	°C
Op	perating case temperature	$T_{c}$		-20	125	°C
Sto	orage temperature	$T_{ m stg}$		-40	125	°C
	older temperature	$T_{sol}$	*9	-	260	°C
	plating voltage	V <sub>isol</sub>	*10	-	2500	Vrms
	ounting torque of screws to heat sink	M <sub>s</sub>	Mounting(M4)	-	1.7	Nm
Mo	ounting torque of screws to terminals	$M_{\rm t}$	Main Terminals(M4)	-	-	Nm
NI.	too	· · · · · · · · · · · · · · · · · · ·				

- \*1:  $V_{CES}$  shall be applied to the input voltage between terminal P-(U,V, W) and (U,V, W)-N.
- \*2: In the case of the load inductance to be over 1µH.
- \*3: Duty=150°C/ $R_{th(i-c)}/(I_F \times V_F \text{ Max.}) \times 100$
- \*4:  $P_{\text{tot}}$ =150°C/ $R_{\text{th(i-c)}}$  \*5:  $V_{\text{CC}}$  shall be applied to the input voltage between terminal No.3 and 1, 6 and 4, 9 and 7,11 and 10.
- \*6:  $V_{\text{in}}$  shall be applied to the input voltage between terminal No.2 and 1, 5 and 4, 8 and 7,12~14 and 10.
- \*7:  $V_{\rm ALM}$  shall be applied to the voltage between terminal No.15 and 10.
- \*8: I<sub>ALM</sub> shall be applied to the input current to terminal No.15.
- \*9: Immersion time 10±1sec. 1time
- \*10: Terminal to base, 50/60Hz sine wave 1min. All terminals should be connected together during the test.

#### **■** Electrical characteristics

#### Main circuit

 $T_{\rm vi}$ =25°C,  $V_{\rm CC}$ =15V unless otherwise specified

	Items	Symbol	Co	nditions	Min.	Тур.	Max.	Units
ē	Collector current at off signal Input	I <sub>CES</sub>	V <sub>CE</sub> :650V		-	ı	1.0	mA
Inverter	Collector-emitter	$V_{\text{CE(sat)}}$	I <sub>c</sub> = 30A	Terminal	-	-	1.80	V
≥	saturation voltage	• CE(sat)		Chip	-	1.40	-	V
	Forward voltage of FWD	$V_{\scriptscriptstyle  extsf{F}}$	I <sub>F</sub> = 30A	Terminal	-	-	2.00	V
	I of ward voltage of 1 VVD	V <sub>F</sub>		Chip	-	1.60	-	V
0	Collector current at off signal Input	I <sub>CES</sub>	V <sub>CE</sub> =-V		-	ı	-	mA
Brake	Collector-emitter	V	I <sub>C</sub> = -A	Terminal	-	ı	-	V
] Sign	saturation voltage	$V_{{\sf CE}({\sf sat})}$		Chip	-	ı	-	V
1	Forward voltage of FWD	$V_{\scriptscriptstyle \sf F}$	I <sub>F</sub> = -A	Terminal	-	ı	-	V
	Torward voltage or T VID	VF		Chip	-	ı	-	V
Switch	hing time	$t_{ ext{on}}$	I <sub>c</sub> = 30A	T <sub>vj</sub> =150°C	0.5	1	-	μs
*11		$t_{\sf d(on)}$	$V_{\rm DC}$ = 300V		0.5	-		μs
		$t_{ m off}$			-	-	2.0	μs
		$t_{d(off)}$			-	-	1.7	μs
		t <sub>rr</sub>	$I_{\rm F}$ = 30A $V_{\rm DC}$ = 300V	T <sub>vi</sub> =150°C	-	-	0.5	μs

<sup>\*11:</sup> Turn on time  $(t_{on}) = t_{d(on)} + t_r$ , Turn off time  $(t_{off}) = t_{d(off)} + t_f$ 

**IGBT Modules** 

### Control circuit

 $T_{vi}$ =25°C,  $V_{CC}$ =15V unless otherwise specified

Item	Symbol	Conditions		Min.	Тур.	Max.	Units
Supply current of P-side	I <sub>ccp</sub>	Switching frequency $(f_{SW}) = 0$	15kHz	-	-	9	mΑ
pre-driver (per one unit)	- сср	$T_{\rm C} = -20 \sim 125^{\circ}{\rm C}$					
Supply current of N-side	1					23	mΑ
pre-driver	I con						
Input signal threshold voltage	$V_{\text{inth(on)}}$	V <sub>in</sub> -GND	ON	1.2	1.4	1.6	V
	$V_{\text{inth(off)}}$	V in OND	OFF	1.5	1.7	1.9	V

#### Protection circuit

 $T_{vi}$ =25°C,  $V_{CC}$ =15V unless otherwise specified

Item	Symbol	Conditions		Min.	Тур.	Max.	Units
Over current Inverter	1	T <sub>vi</sub> =150°C		45	-	-	Α
protection level Brake	I <sub>oc</sub>			-	-	-	Α
Over current protection delay time	$t_{ ext{dOC}}$	T <sub>vj</sub> =150°C		-	4.0	-	μs
Short circuit protection delay time	$t_{ exttt{dSC}}$	$T_{\rm vi}$ =150°C		-	2.0	-	μs
IGBT chips over heating	$T_{jOH}$	Surface of IGBT Chips		175	-	-	°C
protection temperature level	<b>I</b> jOH						
Over heating protection hysteresis	$T_{jH}$			-	20	-	°C
Under voltage protection level	$V_{\scriptscriptstyle UV}$			11.0	ı	12.5	V
Under voltage protection hysteresis	$V_{\scriptscriptstyle H}$			0.2	0.5	-	<b>V</b>
	$t_{\scriptscriptstyle ALM(OC)}$	ALM-GND		1.0	2.0	2.4	ms
Alarm signal hold time	$t_{ALM(UV)}$	T <sub>C</sub> =-20∼125°C	V <sub>cc</sub> ≧10V	3.5	4.0	4.5	ms
	$t_{\text{ALM(TjOH)}}$			7.0	8.0	9.0	ms
Alarm signal voltage	$V_{ALMH}$	ALM-GND, without protection	ſ	14.5	1	15.0	V
Resistance for current limit	$R_{\scriptscriptstyle ALM}$			960	-	1570	Ω

### ■ Thermal resistance characteristics ( $T_c = 25^{\circ}C$ )

Item			Symbol	Min.	Тур.	Max.	Units
Thermal resistance	Inverter	RC-IGBT	$R_{ m th(j-c)}$	-	-	1.12	K/W K/W
junction to case	Brake	IGBT	$R_{ m th(i-c)Q}$	-	-	-	K/W
*12	Diake	FWD	$R_{th(i-c)D}$	-	1	-	K/W
Thermal resistance case to heat sink *13			$R_{ m th(c-s)}$	-	0.05	-	K/W

<sup>\*12:</sup> For 1 device, the measurement point of the case is just under the chip.

### ■ Noise immunity ( $V_{DC}$ =300V, $V_{CC}$ =15V)

Item	Conditions	Min.	Тур.	Max.	Units
1	Pulse width 1µs,polarity ±,10min.	±2.0	-	-	kV
Rectangular noise	Judge: no over-current, no miss operating				

### ■ Recommended operating conditions

Item	Symbol	Min.	Тур.	Max.	Units
DC bus voltage	$V_{ exttt{DC}}$	-	ı	400	V
Power supply voltage of pre-driver	$V_{cc}$	13.5	15.0	16.5	V
Switching frequency of IPM	$f_{_{\mathrm{SW}}}$	-	ı	20.0	kHz
Arm shoot through blocking time for IPM's input signal *14	$t_{\sf dead}$	1.5	-	-	μs
Screw torque (M4)	-	1.3	-	1.7	Nm

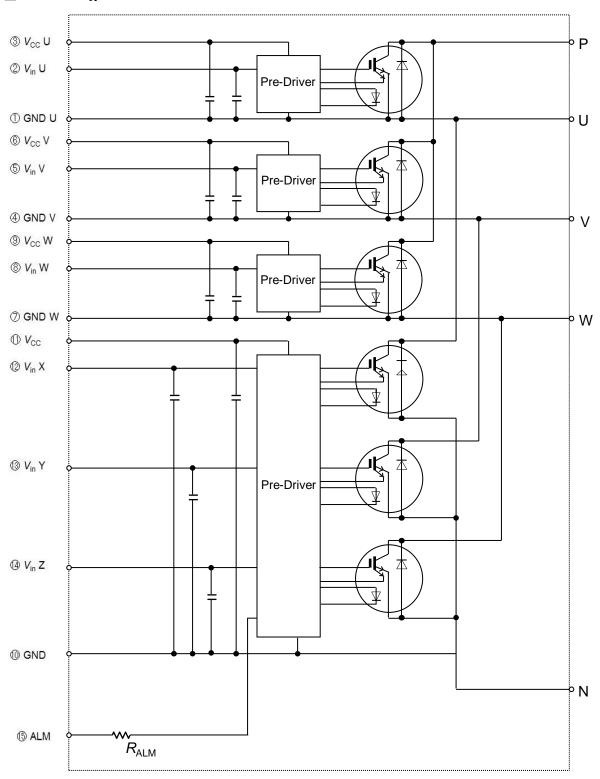
<sup>\*14:</sup>  $t_{\text{dead}} = t_{\text{off}} - t_{\text{d(on)}}$ 

<sup>\*13:</sup> This is the value which is defined mounting on the additional heat sink with 1 W/(m·K) thermal grease.



**IGBT Modules** 

#### ■ Block diagram



Pre-drivers include following functions

- 1. Amplifier for driver
- 2. Short circuit protection3. Under voltage lockout circuit
- 4. Over current protection
- 5. IGBT chip over heating protection

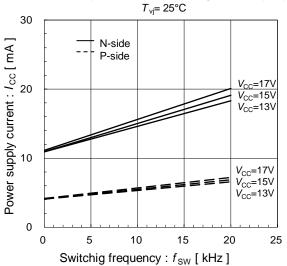


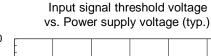
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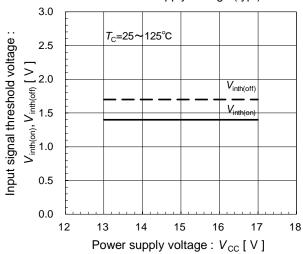
#### ■ Characteristics (representative)

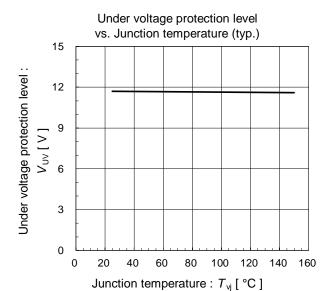
#### **Control circuit**

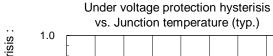
Power supply current vs. switching frequency (typ.)

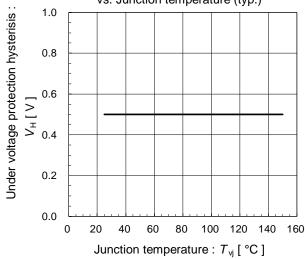


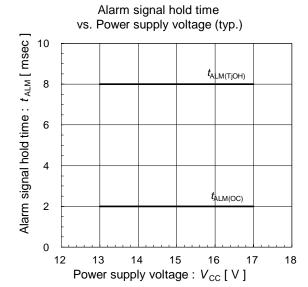


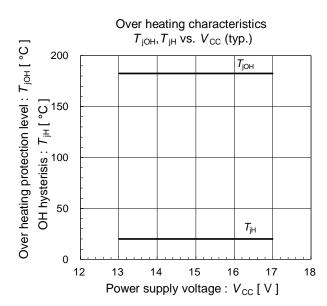






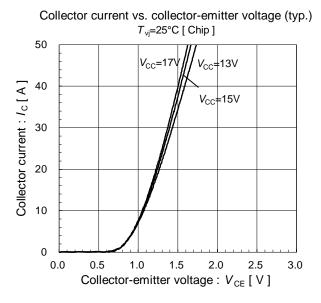


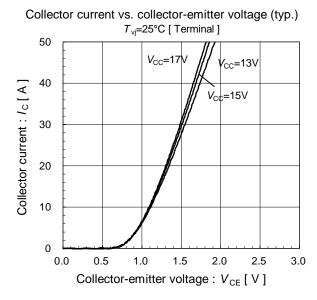


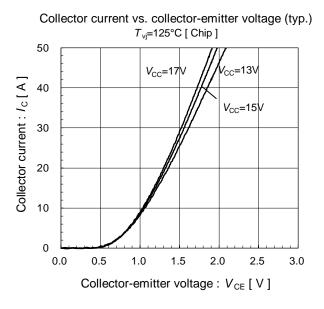


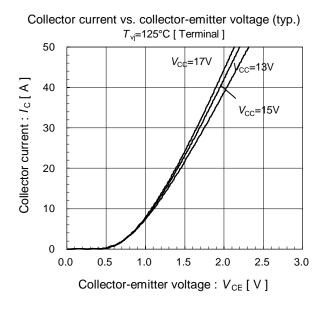
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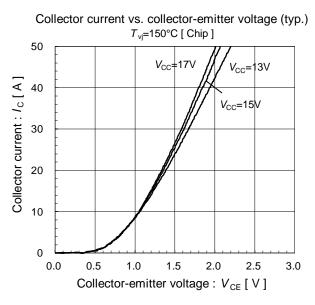
#### Inverter

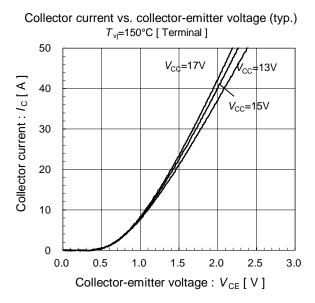






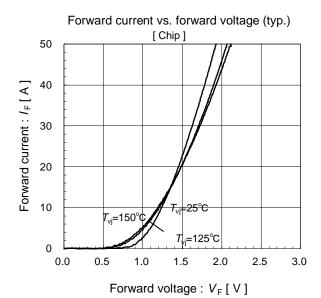


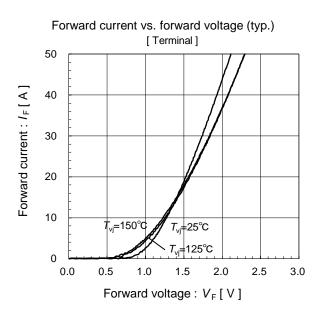


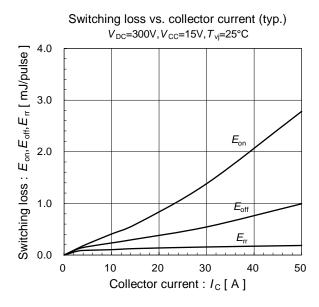


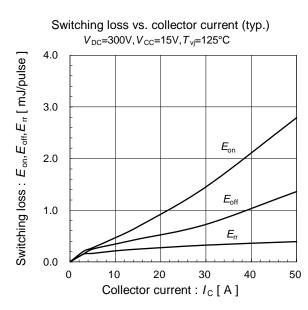


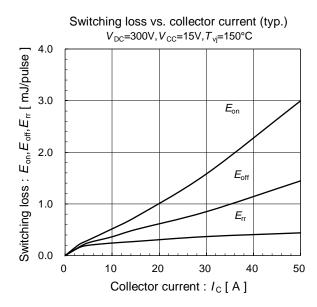
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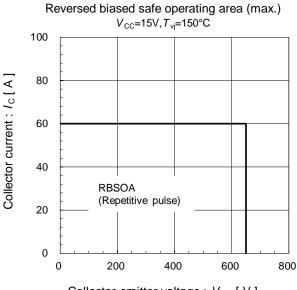


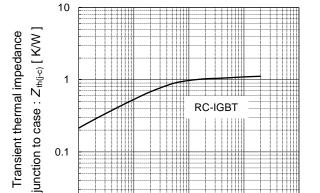




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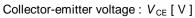


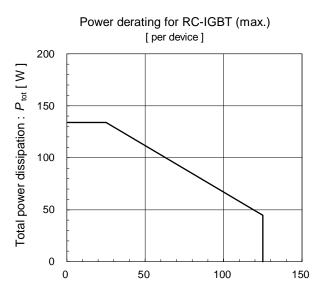
Transient thermal resistance (max.)

Pulse width : Pw [ sec ]

0.01

0.001

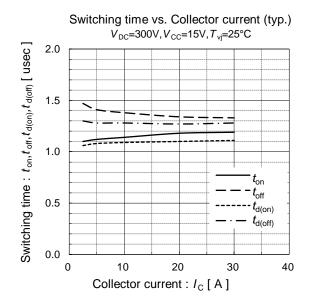


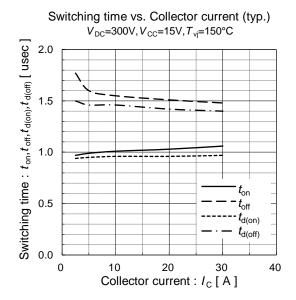


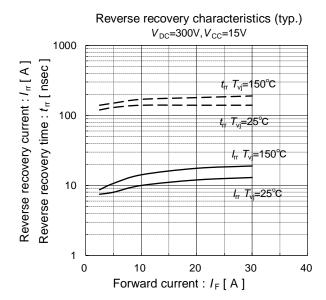
Case Temperature :  $T_{\rm C}$  [ °C ]

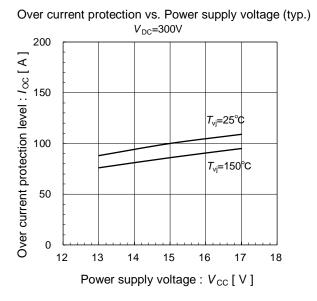


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